



US00D466500S

(12) **United States Design Patent**  
**Lo et al.**

(10) **Patent No.:** **US D466,500 S**  
(45) **Date of Patent:** **\*\* Dec. 3, 2002**

(54) **WEB PAD**

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Hsin-Chu (TW)

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/151,991**

(22) Filed: **Dec. 17, 2001**

(51) **LOC (7) Cl.** ..... **14-02**

(52) **U.S. Cl.** ..... **D14/336**

(58) **Field of Search** ..... D14/341-346,  
D14/390, 371, 374, 336, 125-129; 710/126;  
340/825.52; 370/465; 709/200, 318, 202,  
249, 217, 227; 380/51; 717/11; 707/4

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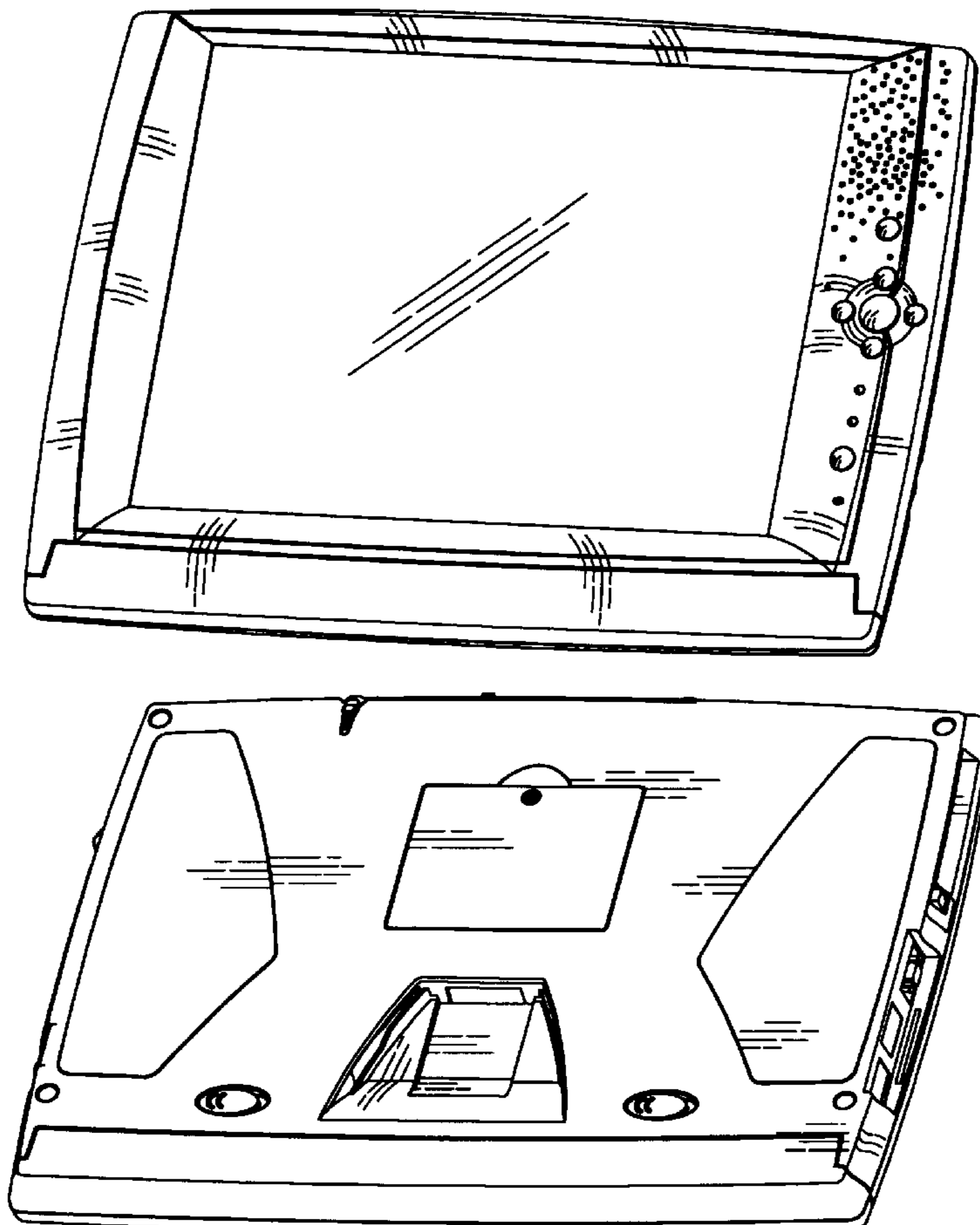
(57) **CLAIM**

The ornamental design for a web pad, as shown and described.

**DESCRIPTION**

FIG. 1 is a front elevational view of a web pad showing our new design;  
FIG. 2 is a rear elevational view thereof;  
FIG. 3 is a left side elevational view thereof;  
FIG. 4 is a right side elevational view thereof;  
FIG. 5 is a top side elevational view thereof;  
FIG. 6 is a bottom side elevational view thereof;  
FIG. 7 is a front perspective view thereof; and,  
FIG. 8 is a rear perspective view thereof.

**1 Claim, 4 Drawing Sheets**



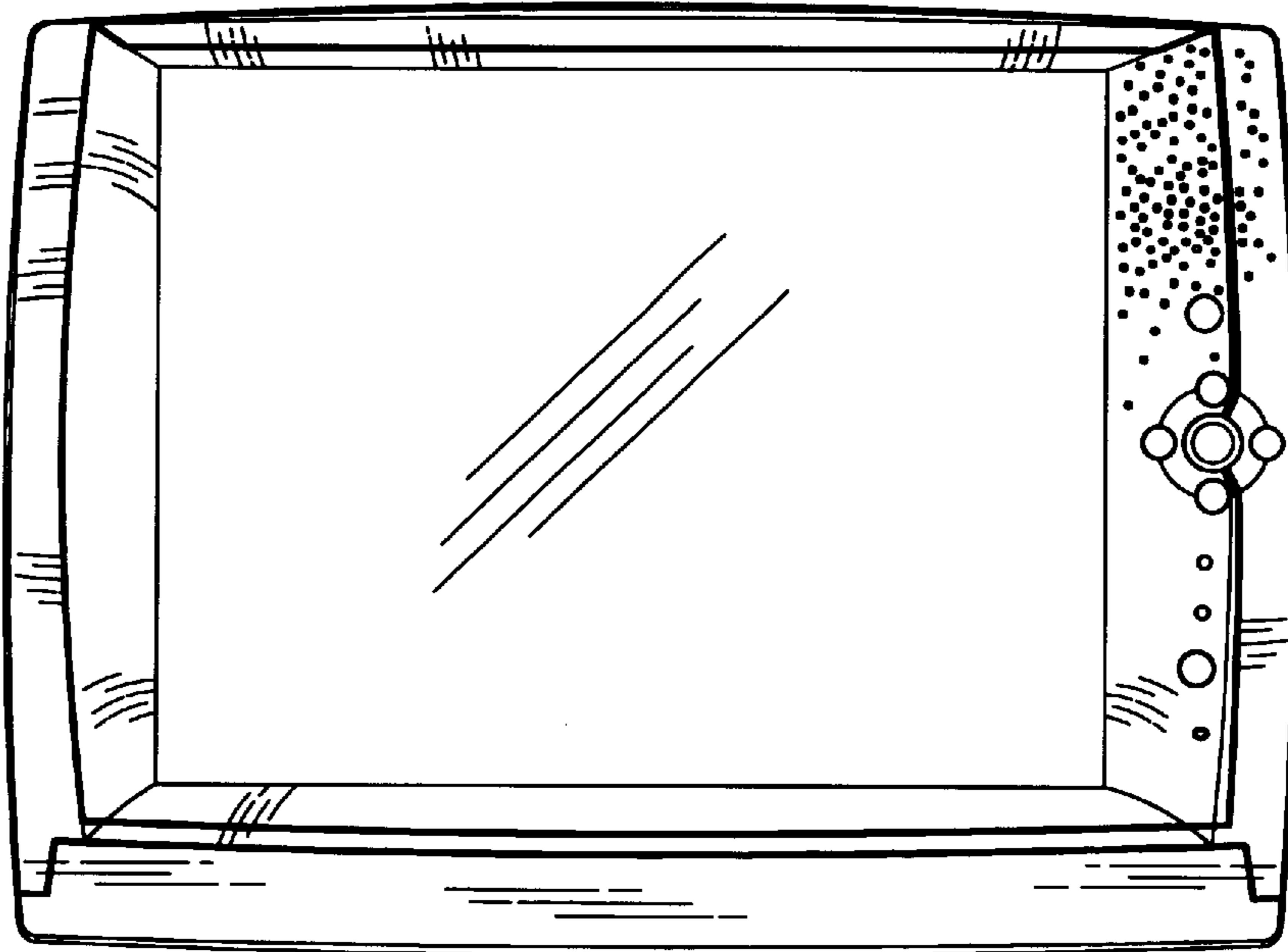


Fig. 1

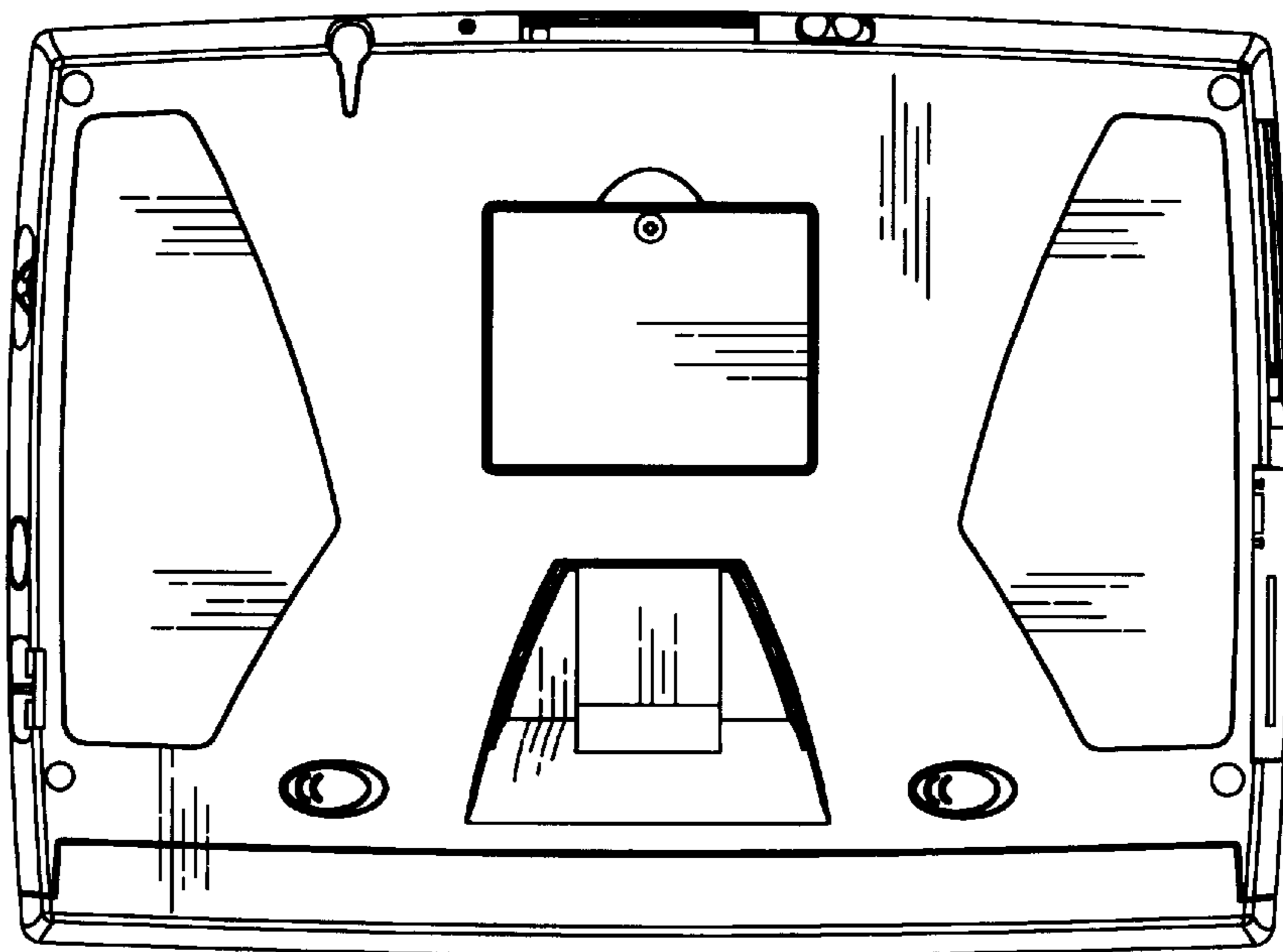


Fig. 2



Fig. 3

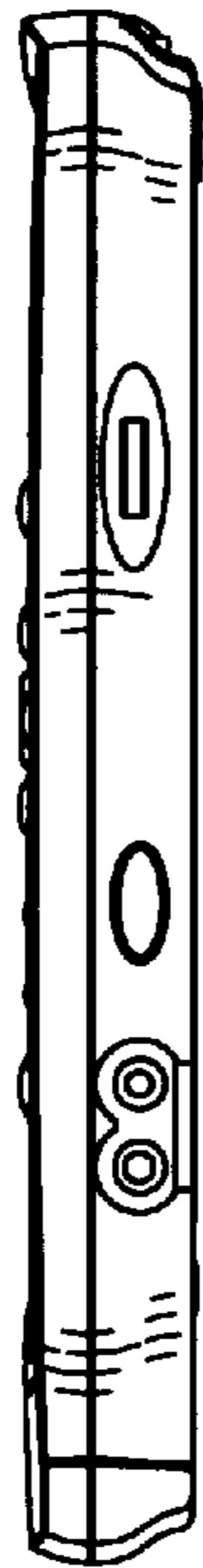


Fig. 4

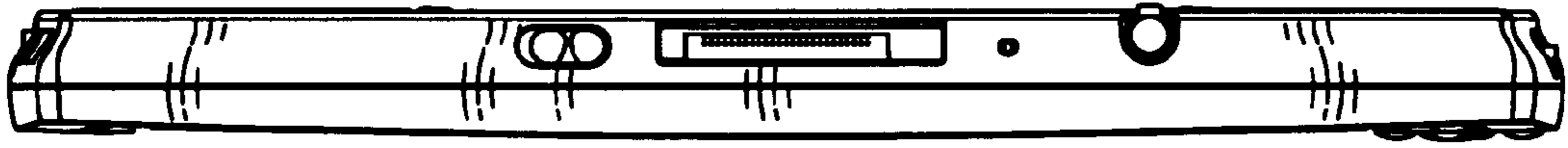


Fig. 5

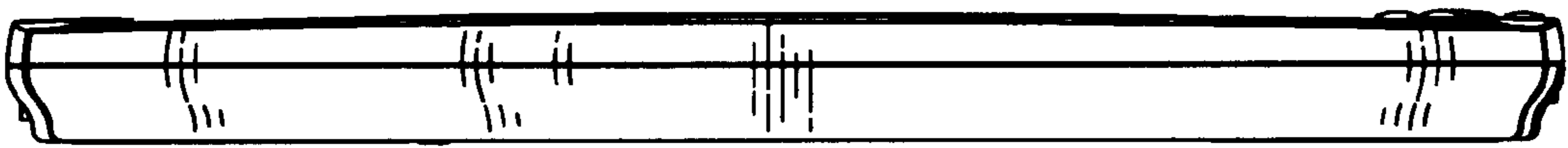


Fig. 6

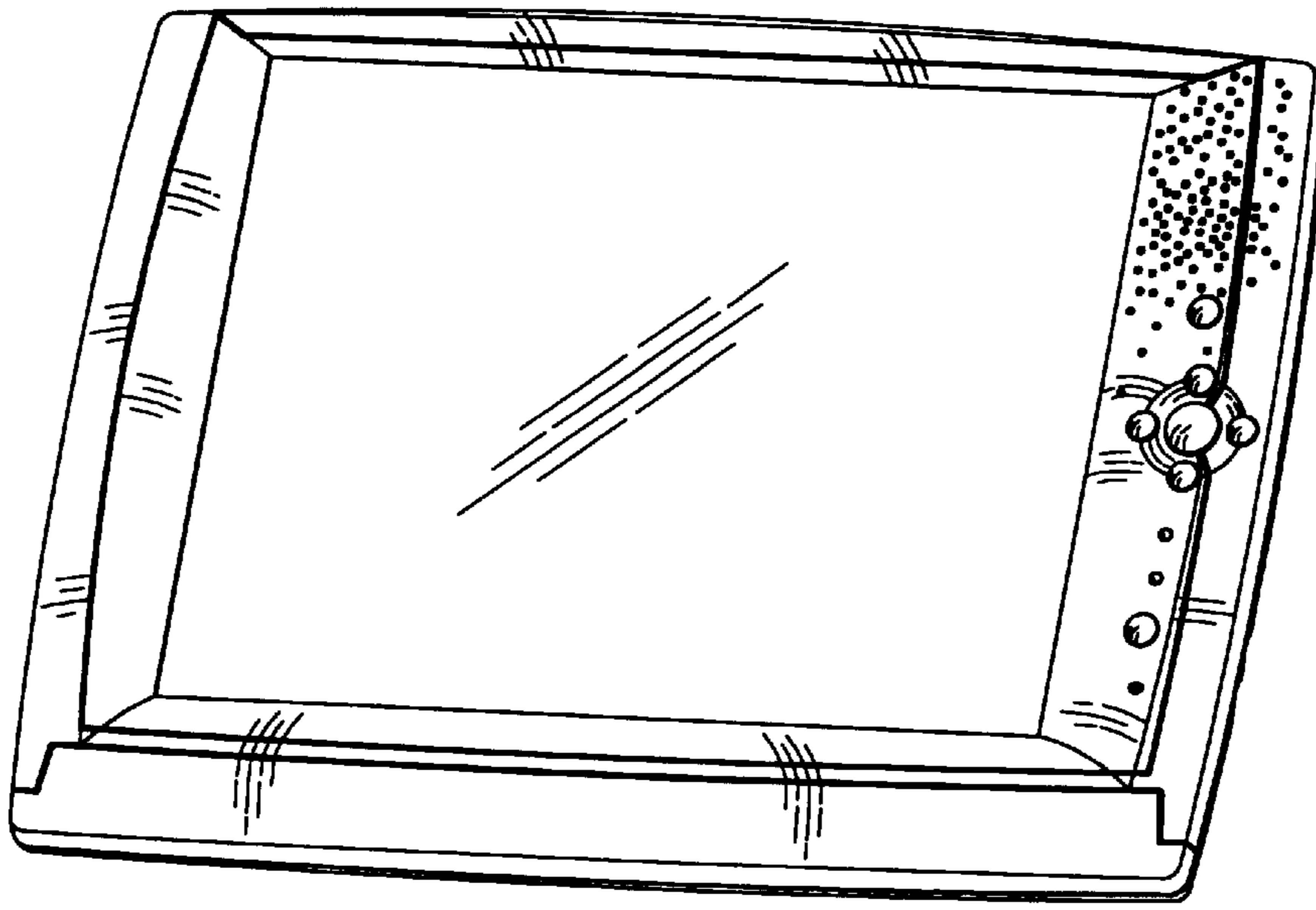


Fig. 7

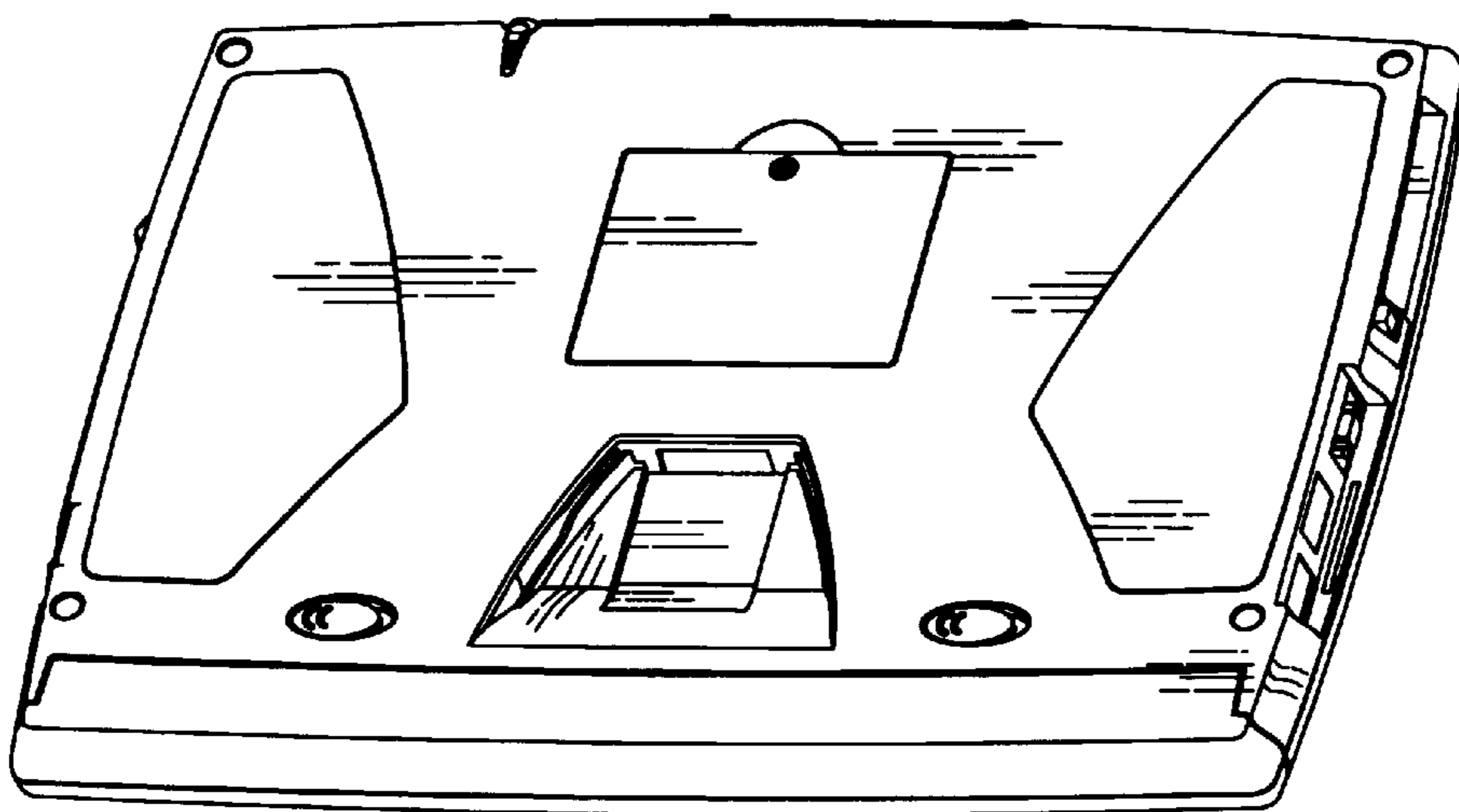


Fig. 8

UNITED STATES PATENT AND TRADEMARK OFFICE  
**CERTIFICATE OF CORRECTION**

PATENT NO. : Des. 466,500 S  
DATED : December 3, 2002  
INVENTOR(S) : Chia-Ching Lo et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title page.

Item [73], Assignee, should read -- **AboCom Systems. Inc.** 1f, No. 21, Yanfa 2<sup>nd</sup> SBIP  
Hsinchu City 300, Taiwan, R.O.C. --.

Signed and Sealed this

Fifteenth Day of November, 2005

A handwritten signature in black ink that reads "Jon W. Dudas". The signature is written in a cursive style with a large, looped initial "J".

JON W. DUDAS

*Director of the United States Patent and Trademark Office*